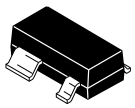
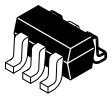
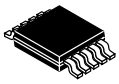


−143
SR SUFFIX
CASE 318A

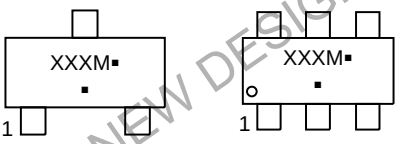
SC−74
SO SUFFIX
CASE 318F



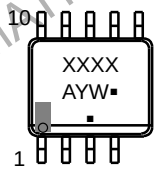
SC70−6
S7 SUFFIX
CASE 419AD



MSOP−10
MR SUFFIX
CASE 846AE



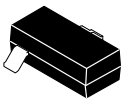
XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package



(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 2 of this data sheet.

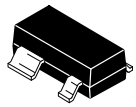


SCALE 4:1

SOT 23 (TO 236) 2.90x1.30x1.00 1.90P
CASE 318
ISSUE AU

DATE 14 AUG 2024

SOT−143

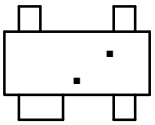


CALE 4:1

	MILLIME E	
DIM	MIN	MA
A	0.80	1.12
	0.30	0.51
1	0.76	0.94
	0.08	0.20
D	2.80	3.05
E1	1.20	1.40
℄	1.92 BSC	
L	0.35	0.70

1 1 2 D 1 1 2 D 1 1 2 D 1 1 2 D2 1 1 2 D2 1 1 2 D2 1 1

GENERIC
MARKING DIAGRAM*

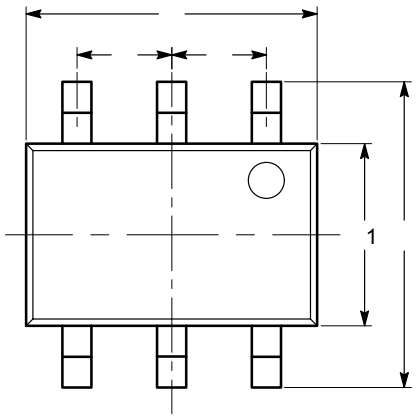


SC−74
CASE 318F
ISSUE P

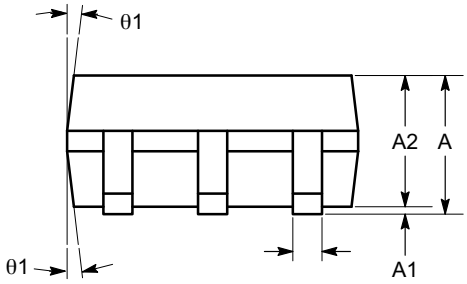
DATE 07 OCT 2021

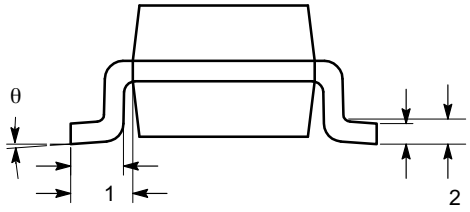
CASE 419AD
ISSUE A

DATE 07 JUL 2010



A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.26	0.36	0.46
L1	0.42 REF		
L2	0.15 BSC		
θ	0		8
θ1	4		10



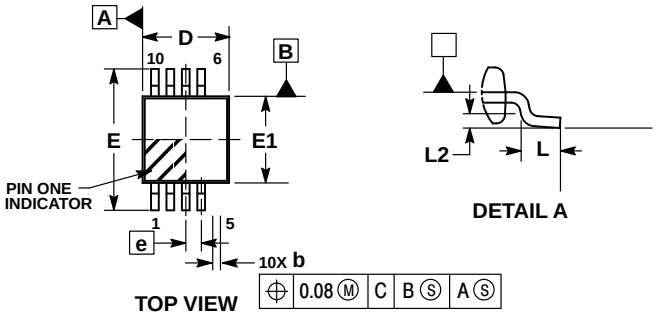


(1) A a . A .
(2) -203.

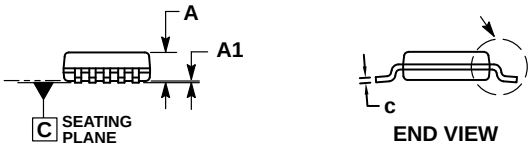
SCALE 1:1

MSOP10, 3x3
CASE 846AE
ISSUE A

DATE 20 JUN 2017



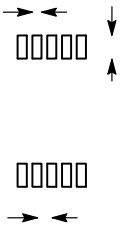
TOP VIEW



SIDE VIEW

END VIEW

RECOMMENDED SOLDERING FOOTPRINT*

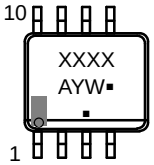


*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DATUMS A AND B TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS	
DIM	MIN	NOM
A	−−−	−−−
A1	0.00	0.05
b	0.17	−−−
c	0.13	−−−
D	2.90	3.00
E	4.75	4.90
E1	2.90	3.00
e	0.50 BSC	
L	0.40	0.70
L1	0.95 REF	
L2	0.25 BSC	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present and may be in either location. Some products may not follow the Generic Marking.